

# CGD942C

870 MHz, 23 dB gain power doubler amplifier

Rev. 01 — 7 June 2007

Product data sheet

## 1. Product profile

### 1.1 General description

Hybrid amplifier module in a SOT115J package, operating at a supply voltage of 24 V (DC), employing Hetero Field Effect Transistor (HFET) GaAs dies.

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

### 1.2 Features

- High output capability
- Excellent linearity
- Extremely low noise
- Excellent return loss properties
- Rugged construction
- Gold metallization ensures excellent reliability

### 1.3 Applications

- CATV systems operating in the 40 MHz to 870 MHz frequency range

### 1.4 Quick reference data

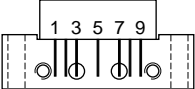
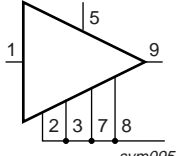
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$G_p$	power gain	$f = 870 \text{ MHz}$	22	23	24	dB
$I_{tot}$	total current	$V_B = 24 \text{ V}$	[1] -	450	-	mA

[1] Direct Current (DC)

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	input		
2, 3	common		
5	+V <sub>B</sub>		
7, 8	common		
9	output		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
CGD942C	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads	SOT115J

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>B</sub>	supply voltage		-	30	V
V <sub>i(RF)</sub>	RF input voltage	single tone	-	75	dBmV
		132 channels flat	-	45	dBmV
T <sub>stg</sub>	storage temperature		-40	+100	°C
T <sub>mb</sub>	mounting base temperature		-20	+100	°C

## 5. Characteristics

**Table 5. Characteristics**

Bandwidth to 870 MHz;  $V_B = 24\text{ V (DC)}$ ;  $T_{mb} = 35\text{ °C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$G_p$	power gain	$f = 870\text{ MHz}$	22	23	24	dB
$SL_{sl}$	slope straight line	$f = 40\text{ MHz to }870\text{ MHz}$	[1] 1	-	2	dB
FL	flatness of frequency response	$f = 40\text{ MHz to }870\text{ MHz}$	[2] -	0.5	-	dB
CTB	composite triple beat	79 + 53 flat NTSC channels	[3] -	-68	-66	dB
		98 flat PAL channels	[4] -	-66	-	dB
CSO	composite second-order distortion	79 + 53 flat NTSC channels	[3] -	-70	-67	dB
		98 flat PAL channels	[4] -	-66	-	dB
Xmod	cross modulation	79 + 53 flat NTSC channels	[3] -	-66	-58	dB
$RL_{in}$	input return loss	$f = 40\text{ MHz to }80\text{ MHz}$	20	-	-	dB
		$f = 80\text{ MHz to }160\text{ MHz}$	19	-	-	dB
		$f = 160\text{ MHz to }320\text{ MHz}$	18	-	-	dB
		$f = 320\text{ MHz to }640\text{ MHz}$	18	-	-	dB
		$f = 640\text{ MHz to }870\text{ MHz}$	18	-	-	dB
$RL_{out}$	output return loss	$f = 40\text{ MHz to }80\text{ MHz}$	20	-	-	dB
		$f = 80\text{ MHz to }160\text{ MHz}$	19	-	-	dB
		$f = 160\text{ MHz to }320\text{ MHz}$	18	-	-	dB
		$f = 320\text{ MHz to }640\text{ MHz}$	18	-	-	dB
		$f = 640\text{ MHz to }870\text{ MHz}$	18	-	-	dB
NF	noise figure	$f = 50\text{ MHz}$	-	3.5	5.0	dB
		$f = 870\text{ MHz}$	-	3.5	5.0	dB
$I_{tot}$	total current	$V_B = 24\text{ V}$	[5] -	450	-	mA

[1]  $G_p$  at 870 MHz minus  $G_p$  at 40 MHz.

[2] Flatness straight line (peak to valley).

[3] 79 NTSC channels: 55.25 MHz to 547.25 MHz, 48 dBmV output level; + 53 NTSC channels 553.25 MHz to 997.25 MHz, 38 dBmV output level.

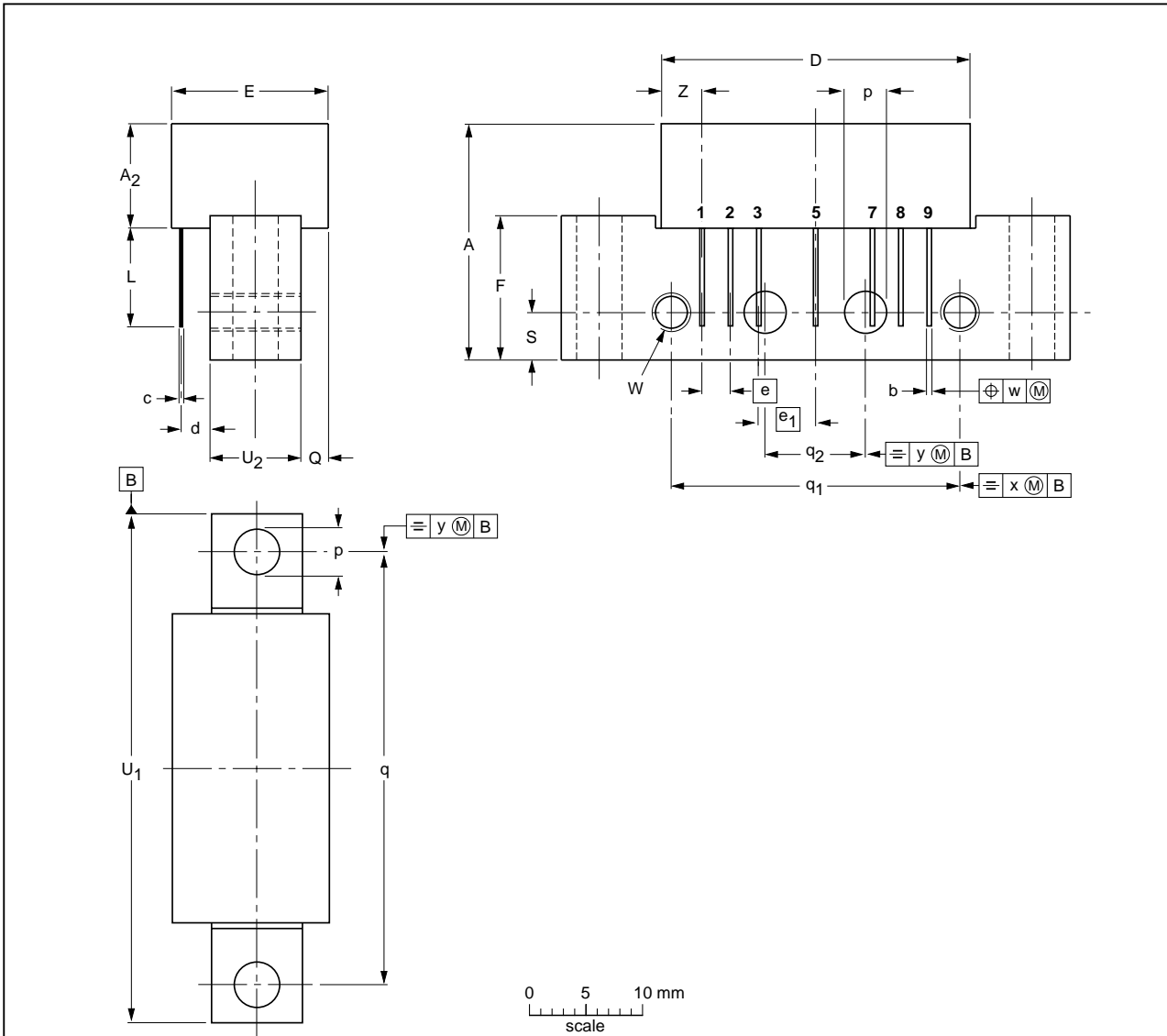
[4]  $V_o = 48\text{ dBmV}$ .

[5] Direct Current (DC).

## 6. Package outline

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads

SOT115J



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>2</sub> max.	b	c	D max.	d max.	E max.	e	e <sub>1</sub>	F	L min.	p	Q max.	q	q <sub>1</sub>	q <sub>2</sub>	S	U <sub>1</sub>	U <sub>2</sub>	W	w	x	y	Z max.
mm	20.8	9.1	0.51 0.38	0.25	27.2	2.54	13.75	2.54	5.08	12.7	8.8	4.15 3.85	2.4	38.1	25.4	10.2	4.2	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	3.8

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115J						99-02-06 04-02-04

Fig 1. Package outline SOT115J

## 7. Abbreviations

**Table 6. Abbreviations**

Acronym	Description
CATV	CABle TeleVision
DC	Direct Current
NTSC	National Television Standard Committee
PAL	Phase-Alternation Line
RF	Radio Frequency
UNC	UNified Coarse thread

## 8. Revision history

**Table 7. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
CGD942C_1	20070607	Product data sheet	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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